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Design Procedure for Millimeter-Wave InP DHBT Stacked Power Amplifiers

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Outline

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- Technology
- Stacked Transistors Configuration
- Procedure for Power Cell Design
- Preliminary Results
 - Proof of concept
 - Implementation
- Conclusions



Background and Motivation

- Wireless communications are increasingly taking place at E-band (71-76 GHz, 81-86 GHz) and higher millimeter-wave frequencies
 - Large absolute bandwidth
 - Low atmospheric attenuation
 - Small system size
- The main limitations are imposed by the power amplifier of the transmitter ($P_{Tx} \sim 1/f^2$)



Background and Motivation

 InP DHBT technology offers high frequency of operation and high density of integration with moderate breakdown voltage



• Geometrical downscaling

Breakdown voltage reduction



Investigation and design of new topologies

Technology

• InP DHBT Technology developed at III-V Lab

- 1-finger device performances $\beta \sim 40$ BV_{CE0}~ 4.9V f_T ~ 330 GHz f_{max} ~ 420 GHz
- 4-finger device performances f_T ~ 270 GHz Up to 360 GHz f_{max}
- 4-finger HBTs with ballasting Better « SOA » f_T~ 200 GHz f_{max}< 300 GHz







Stacked Transistors Configuration



- Overall output voltage *n* times larger than a single device
- Current swing is the same

- Output power n times higher
- Output voltage equally distributed among the devices
- Phase alignement required



Procedure for Power Cell Design

- Nonlinear UCSD HBT model
- Load-Pull simulation for the common-emitter stage (Z_{opt,1})
- The input impedance of the second stage must have the same value



Procedure for Power Cell Design

- The same procedure is repeated for the following stages
- Once Y_{L,k} is found for the k-th stage, a load pull simulation can be performed on the k-transistor power cell to check if its value is close to the optimum



Preliminary Results (Proof of concept)

• InP DHBT single finger devices BV_{CE0}=4.9 V; f_T/f_{max}=330/420 GHz @ V_{ce}=2.4 V and I_c=15 mA







Preliminary Results (Proof of concept)



The design of the two- and three-stack power cells are intermediate steps for the design of the four-stack





Preliminary Results (Implementation)

• 2 stacked single finger transistors



Preliminary Results (Implementation)

• 2 stacked ballasted four-finger transistors





Conclusions

- Possibility to apply the transistor-stacking concept to InP DHBT power amplifier operating at millimeter-wave frequencies
- An effective design procedure has been described and applied to two different four-transistor stacked power cells operating at 86 GHz and 140 GHz

Perspectives

- Realization of three- and four-stack power cells
- Investigation on efficient topologies for impedance matching
- Parallel combination of multiple power cells (e.g. Wilkinson, baluns...)









Thank you for your attention!

